OSFP

Product Description

The OSFP interconnect system has 60 contacts per port and supports 16 high speed pairs. With a 0.6mm contact pitch, 4 rows of contacts and a horizontal port pitch of 23.38mm, the OSFP footprint is optimized for signal integrity performance. The stacked connector is enhanced for low crosstalk and has ground commoning for resonance dampening. It is also designed for 1U applications. An integrated heat sink for optimal thermal performance is a feature of the design.

Applications	
Storage	Cellular infrastructure
Network Interface	Hubs and Servers
Test and measurement equipment	Switches

Supported Standards	
OSFP MSA	

Product Specifications - OSFP		
CONNECTOR		
Materials Specifications		
Housing	Black color, Glass reinforced , Lead Free Solder Reflow Process Compatible Thermo Plastic	
Contacts Base Material	Copper Alloy C7025	
Contact Normal Force	40 grams min.	
Plating Solder Tails	Matte tin over Nickel	
Plating Mating Area	Gold	
Resonance Dampening Feature	Carbon fibre reinforced	
Operating & Storage Temperature	-20° to +85° C	
Electrical Specifications		
Operating Voltage	30 VDC per contact	
Operating Current	0.5 A per signal contact1.5 A per low speed power contact	
Differential Impedance	100 Ω +/- 10 Ω	
Mechanical Specifications		
Mating Force	40 N max.	
Unmating Force	40 N max.	
Durability	250 mating cycles	
Options		
Packaging	Tape and Reel or Tray	
Configurations	1x1, 1x4, 2x6	
Environmental Specifications		
RoHS	Yes	
Halogen Free	Yes	
Flammability Rating	UL 94V-0	





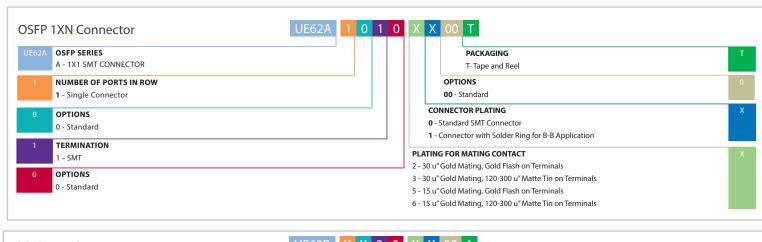


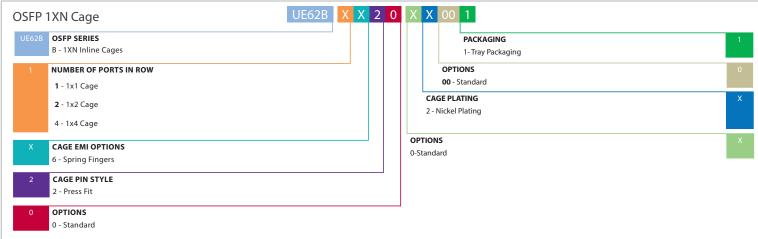


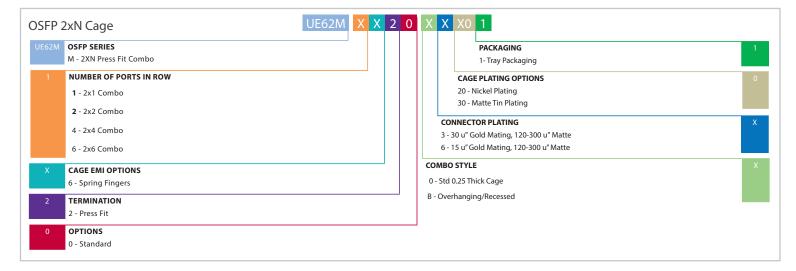




Ordering Information









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